Cooperation Agreement for Small Form Factor Transceivers

AMP Inc., Hewlett-Packard Company, Lucent Technologies Inc., Nortel plc, Siemens AG Semiconductors, Sumitomo Electric Lightwave Corp.

I. Purpose of the Cooperation Agreement

Each party desires to establish internationally compatible sources of a fiber optic transceiver module in support of standards for fiber optic systems including Asynchronous Transfer Mode (ATM), FDDI, Fibre Channel, Fast Ethernet and Gigabit Ethernet, and Synchronous Optical Network (SONET)/Synchronous Digital Hierarchy (SDH) applications.

Each party further desires to establish uniformity in the industry for the Transceiver "Package Outline", "Circuit Board Layout" and "Pin Function Definitions" described in Appendix A.

Each party expects that the establishment of compatible sources for an interchangeable transceiver module will allow the entire fiber optic market to grow more rapidly. This enhanced market growth is the express purpose of the Agreement.

The parties desire to establish compatible sources for additional products in the future.

II. Agreement

A. General

The parties agree to cooperate by supporting common product specifications for fiber optic transceivers with the package "Package Outline", "Circuit Board Layout" and "Pin Function Definitions" described here and in Appendix A. Initial products utilizing this agreement may include Fiber Optic Transceivers at 100 to 1250 Mb/s for multimode and single mode fiber applications. Other fiber optic transceivers may follow as needed in the marketplace.

The mechanical dimensions shall be compatible with the package "Package Outline", "Circuit Board Layout" and "Pin Function Definitions" as shown in Appendix A. The overall package dimensions shall not exceed the maximum indicated dimensions, and the pins and mounting posts shall be located such that the products are mechanically interchangeable in a circuit board.

The electrical and optical specifications shall be compatible with those enumerated in the appropriate standards (i.e. the IEEE 802.3z Gigabit Ethernet standard and the ITU G.957 Synchronous Digital Hierarchy standard). In addition, the parties may work together to recommend circuit layouts for electrical input and output terminations, and grounding practices.

The transceivers per this agreement will accept an optical connector such as the duplex LC, MT-RJ or the SC/DC connector. This agreement does not preclude any of the parties from offering Small Form Factor transceivers for other connectors.

Internal design of the product is entirely at the discretion of each party and is not covered by this Agreement.

The parties recognize that their products may not be identical, but need only meet the above criteria.

B. Licensing and Fees

No technology licenses are granted herein and no fees for any such licenses are payable hereunder. However, the parties are not aware of any patents which would interfere with activities under this Agreement.

Each party is free to seek technology or other exchanges with other firms in order to support its activities under this Agreement.

C. Scope of the Agreement

The scope of this Agreement includes transceiver modules for transmission rates from 100 to 1250 Mb/s operating over multimode and single mode fiber.

Each party agrees to be responsible for its own development, manufacturing and selling in order to supply transceiver modules meeting the attached specifications.

This Agreement does not preclude any party from offering other products which may not meet the attached specifications.

Each party retains complete liberty regarding its methods of implementing a supply of product, e.g. by engineering effort or by technology licensing or transfer.

Each party also retains sole discretion in its choice of sales channels and distribution.

Each party affirms its intention to freely and openly compete in the market place with the parties as well as other competitors.

Each party expects to support products meeting the attached specifications for as long as market conditions warrant. No specific time limit is associated with this Agreement. The determination of market condition suitability is to be made by each party individually and in each party's sole discretion.

III. Public Announcement

A. Announcing the Agreement

Each party agrees to announce this Agreement in a manner agreed upon by the parties. These announcements will mention all the parties who have signed this agreement.

Each party agrees to seek maximum public attention by means of such an announcement.

Each party agrees to contribute time and effort toward preparing and making such an announcement.

B. Promotion of the Agreement

After the Agreement is announced, each party may advertise or otherwise promote this Agreement in any way it deems appropriate. Mutual consent of the other party is required if the other party is to be mentioned by name.

IV. Other Vendors

A. Other Vendors Matching the Product Configuration

The parties recognize that additional vendors may choose to match the attached product specifications after this Agreement is announced.

Each party recognizes it is desirable and keeping with the intent of the Agreement for such additional vendors to support the transceiver mechanical dimensions and functional attributes described in Appendix A.

Therefore, each party agrees to encourage other vendors to support these product specifications.

B. Naming Other Vendors

Each party agrees to name the other parties when customers ask who intends to be a second source for the transceivers described in this Agreement. Each party agrees to name the others regardless as to whether another of the parties has already supplied similar transceiver module products to that customer.

An example of suggested wording is; "AMP, Hewlett-Packard, Lucent, Nortel, Siemens, and Sumitomo have signed a Cooperation Agreement relating to the establishment of Small Form Factor transceivers for multimode and single mode fiber operating in the range of 100 to 1250 Mb/s data rates."

The parties are not obligated to provide any information other than the identities of the other parties.

V. Future Direction

A. Current Product

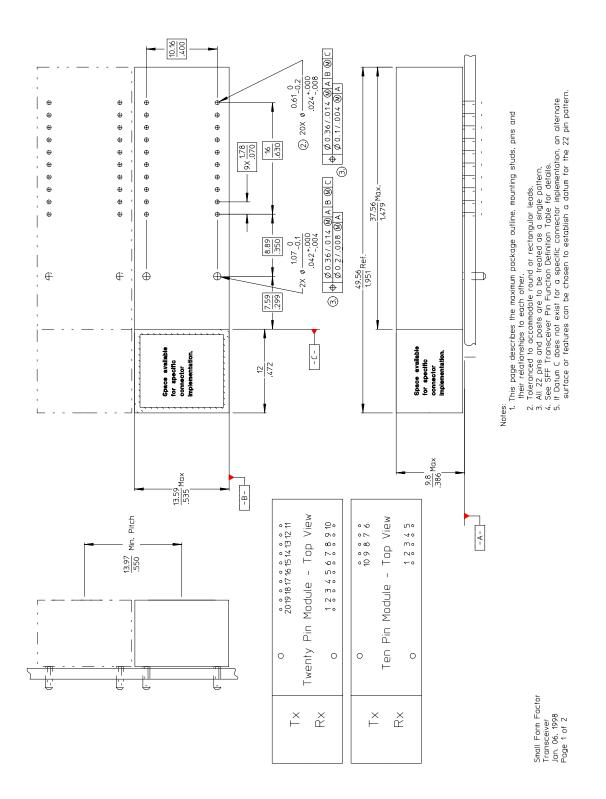
Should the parties agree to further explore technical and other exchanges pertaining to the products described in this Agreement, then this shall be under a separate agreement.

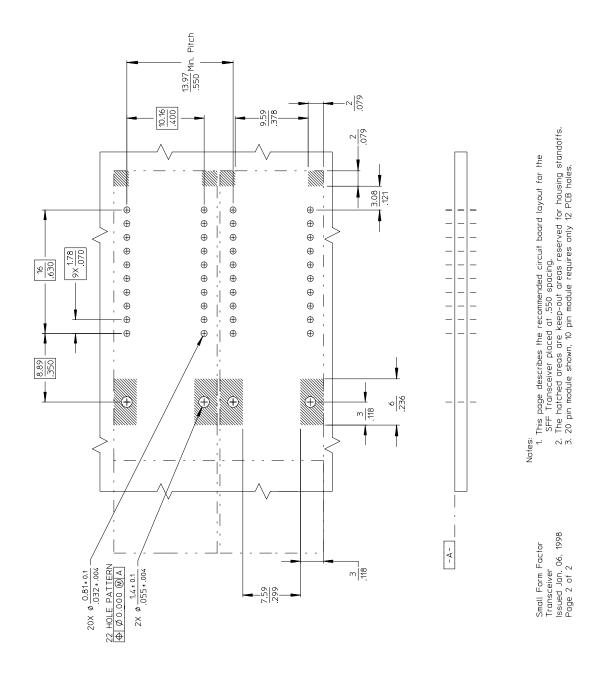
B. Withdrawal

The parties recognize that at some future time it may become less feasible to offer the products envisioned by this Agreement. A party may withdraw from its commitment to cooperate at its own discretion upon a 90-day notice to the other parties. This notice is necessary to allow the other parties to discontinue mentioning the withdrawing party as a participant in this Cooperation Agreement and to reconsider any jointly planned promotional activities.

VI. Agreement Signatures







Appendix A.1.2 Circuit Board Layout

Appendix A.2.1 Transceiver Receiver Pin Function Definitions								
10 and 20 Pin Part Versions (See Package Outline Drawing for Pin Positions within the Package.)				Two versions of this transceiver are intended. The 10 pin version is intended for applications where the extra features of the 20 pin version are not required. The 20 pin version provides extra pins for features beyond data in and out such as recovered clock and laser transmitter monitors and alarms.				
10 Pin Part	20 Pin Part	Symbol	Notes	Functional Description	Logic Family			
MS	MS	MS	The holes in the circuit board must be tied to chassis ground.	Mounting Studs The mounting studs are provided for transceiver mechanical attachment to the circuit board. They may also provide an optional connection of the transceiver to the equipment chassis ground.	N/A			
No Pin	1	Photo- detector Bias	This hole in the circuit board must be tied to the most positive power supply.	Photodetector Bias: Optional Feature This lead supplies bias for the PIN photodetector diode when provided as a feature of a transceiver.	N/A			
No Pin	2	Vee _r		Receiver Signal Ground	N/A			
No Pin	3	Vee _r		Receiver Signal Ground	N/A			
No Pin	4	Clk-	If feature not used do not connect.	Received Recovered Clock Out Bar: Optional Feature The rising edge occurs at the rising edge of the Received Data output. The falling edge occurs in the middle of the Received Data baud period.	PECL			
No Pin	5	Clk+	If feature not used do not connect.	Received Recovered Clock Out: Optional Feature The falling edge occurs at the rising edge of the Received Data output. The rising edge occurs in the middle of the Received Data baud period.	PECL			
1	6	Vee _r		Receiver Signal Ground	N/A			
2	7	Vcc _r		Receiver Power Supply	N/A			
3	8	SD		Signal Detect Normal Operation: Logic "1" Output Fault Condition: Logic "0" Output This signal will be TTL for all gigabit/sec transceivers. For legacy applications (622 Mb/s and below), PECL will be provided.	TTL is preferred, but PECL may be provided			
4	9	RD-		Received Data Out Bar No internal terminations will be provided.	PECL			
5	10	RD+		Received Data Out No internal terminations will be provided.	PECL			

Арр	endix	A.2.2 Tr	ansceive	r Transmitter Pin Function Definitions	
10 and 20 Pin Part Versions (See Package Outline Drawing for Pin Positions within the Package.)				Two versions of this transceiver are intended. The 10 pin version in intended for applications where the extra features of the 20 pin version are not required. The 20 pin version provides extra pins for features beyond data in and out such as recovered clock and laser transmitter monitors and alarms.	
10 Pin Part	20 Pin Part	Symbol	Notes	Functional Description	Logic Family
MS	MS	MS	The holes in the circuit board must be tied to chassis ground.	Mounting Studs The mounting studs are provided for transceiver mechanical attachment to the circuit board. They may also provide an optional connection of the transceiver to the equipment chassis ground.	N/A
6	11	Vcct	2	Transmitter Power Supply	N/A
7	12	Veet		Transmitter Signal Ground	N/A
8	13	TDis	Optional use for Laser based products only	Transmitter Disable:Optional FeatureTransmitter Output Disabled: $(Vcc_t - 1.3V) < V < Vcc_t$ Transmitter Output Enabled: $Vee_t < V < (Vee_t + 0.8V)$ or open circuit	TTL
9	14	TD+		Transmitter Data In An internal 50 ohm termination will be provided for gigabit/sec transceivers consisting of a 100 ohm resistor between the TD+ and TD- pins. No internal termination will be provided for lower speed parts (622 Mb/s and below).	PECL
10	15	TD-		Transmitter Data In Bar See TD+ pin for terminations.	PECL
No Pin	16	Vee _t		Transmitter Signal Ground	N/A
No Pin	17	Bmon(-)	If feature not used do not connect.	Laser Diode Bias Current Monitor - Negative End: Optional Feature The laser bias current is accessible as a dc-voltage by measuring the voltage developed across pins 17 and 18. Dividing the voltage by 10 ohms will yield the value of the laser bias current. The stand-off resistors should be 3k ohms. At an ambient of 25 deg C, the voltage should range up to a maximum of 0.70 volts.	N/A
No Pin	18	Bmon(+)	If feature not used do not connect.	Laser Diode Bias Current Monitor - Positive End: Optional Feature See pin 17 description.	N/A
No Pin	19	Pmon(-)	If feature not used do not connect.	Laser Diode Optical Power Monitor - Negative End: Optional Feature The backface diode monitor current is accessible as a voltage proportional to the photocurrent through a 200 ohm resistor between pins 19 and 20. The stand-off resistors should be 3k ohms. At a 50% duty cycle, this voltage can range between 0.01 and 0.20 volts.	N/A
No Pin	20	Pmon(+)	If feature not used do not connect.	Laser Diode Optical Power Monitor - Positive End: Optional Feature See pin 19 description.	N/A